

# 2010 EDITORIAL CALENDAR

2D/3D and DEVICE ASSEMBLY,  
PACKAGING, INTERCONNECTS  
and MATERIALS

WAFER-LEVEL PACKAGING  
(WLP) BACK-END  
PROCESSING ARTICLES

SHOW and CONFERENCE EXTRA  
DISTRIBUTION

## January/February 2010

Space: Jan 8

Materials: Jan 15

- 3D Technology Trends
- Sockets for Emerging Packaging
- Business: Buying New or Refurbished Equipment

- Wafer Thinning:
- Latest Market Demands in Die Sorting
- WLP--TSV Interconnects

- Meptec Q1 Symposium: San Jose, CA (Feb25)
- BITS Workshop: Mesa, AZ (Mar. 7-10)
- IMAPS Device Pkg: Scottsdale, AZ (Mar 10-12)
- SEMICON China: Shanghai China (Mar 16-18)

## March/April 2010

Space: Feb 24

Materials: Mar 3

- IC Packaging Foundries/OSATS Packaging Assembly and Test Directory
- Adhesives and Coatings
- Die Attach Films
- Thin Film Advancements
- Business: Obsolescence Management

- Wafer Bumping Services

- APEX Expo: Las Vegas, NV (Apr. 6-8)
- Meptec Q2 MEMS Symposium: San Jose, CA (May 20)

## May/June 2010

Space: Apr 26

Materials: May 3

- Die and Flip Chip Bonders
- Thermal Control
- AOI, Acoustic, and X-Ray Inspection
- Business: Outsourcing Office Management

- ECTC/ITHERM: Las Vegas, NV (Jun 2-3)

## July/August 2010

Space: Jun 11

Materials: Jun 18

- Dispensing , Encapsulants & Underfill
- IC Package Design
- Photovoltaic Assembly
- Business: Outfitting a Clean Room

- Wafer Handling of Thinned Wafers

- SEMICON West: San Francisco (Jul 13-15)
- SEMICON Taiwan: Taipei, Taiwan (Sept 8-10)

## September/October 2010

Space: Aug 27

Materials: Sep 3

- MEMS for Medical Applications
- Nanotechnology Materials
- Stencil Printing
- Wire Bonding
- Singulation & Dicing
- Business: Improving First Pass Yields

- WLP - Testing

- ATE: Rosemont, IL (Sept 28-30)
- IWLPC - Intl Wafer-Level Packaging Conference Santa Clara, CA (Oct 11-14)
- SEMICON Europa: Dresden, Germany (Oct 19-21)
- SMTA International: Orlando, FL (Oct 24-28)
- IMAPS: Raleigh, NC (Oct 31-Nov 4)
- ITC - International Test Conference: Austin, TX (Nov 2-4)
- KGD Workshop Santa Clara, CA (TBD)
- Meptec MEMS for Medical Applications (TBD)

## November/December 2010

Space: Oct 26

Materials: Nov 2

- 3D Packaging Applications
- Reflow Soldering
- Automotive Package Applications
- Test and Burn-in Sockets Vendor Directory
- HDI Substrates
- Business: Personnel Training and Certification

- Wet and Plasma Cleaning
- Wafer Probing

- SEMICON Japan : Chiba, Japan (Dec 1-3)